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(54) **SEMICONDUCTOR MODULE AND METHOD  
FOR MANUFACTURING SEMICONDUCTOR  
MODULE**

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**ABSTRACT**

A semiconductor module comprises a semiconductor element, a joining part configured including a sintered metal, a substrate member, and a lead frame. The joining part comprises: at least one element joining member that joins the semiconductor element and a main surface of the substrate member; and at least one lead frame joining member that joins the lead frame and the main surface of the substrate part, the at least one lead frame joining member having a small-piece form with the same volume as the element joining member.

